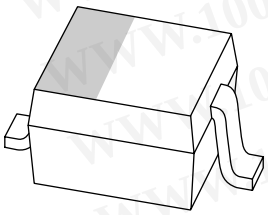
DATA SHEET



BAS321
General purpose diode

Product data sheet
Supersedes data of 1999 Feb 09

2004 Jan 26

founded by Philips

General purpose diode

BAS321

FEATURES

- Small plastic SMD package
- Switching speed: max. 50 ns
- General application
- Continuous reverse voltage: max. 200 V
- Repetitive peak reverse voltage: max. 250 V
- Repetitive peak forward current: max. 625 mA.

APPLICATIONS

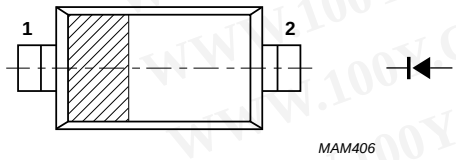
- General purpose switching in e.g. surface mounted circuits.

DESCRIPTION

The BAS321 is a general purpose diode fabricated in planar technology and encapsulated in a plastic SOD323 package.

PINNING

PIN	DESCRIPTION
1	cathode
2	anode



Marking code: A7
The marking bar indicates the cathode.

Fig.1 Simplified outline (SOD323) and symbol.

ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
BAS321	–	plastic surface mounted package; 2 leads	SOD323

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{RRM}	repetitive peak reverse voltage		–	250	V
V_R	continuous reverse voltage		–	200	V
I_F	continuous forward current	see Fig.2; note 1	–	250	mA
I_{FRM}	repetitive peak forward current	t_p < 0.5 ms; $\delta \leq 0.25$	–	625	mA
I_{FSM}	non-repetitive peak forward current	square wave; T_j = 25 °C prior to surge; see Fig.4			
		t = 1 μs	–	9	A
		t = 100 μs	–	3	A
		t = 10 ms	–	1.7	A
P_{tot}	total power dissipation	T_{amb} = 25 °C; note 1	–	300	mW
T_{stg}	storage temperature		–65	+150	°C
T_j	junction temperature		–	150	°C

Note

1. Device mounted on an FR4 printed circuit-board.

General purpose diode

CHARACTERISTICS

T_j = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MAX.	UNIT
V_F	forward voltage	see Fig.3		
		I_F = 100 mA	1	V
		I_F = 200 mA	1.25	V
I_R	reverse current	see Fig.5		
		V_R = 200 V	100	nA
		V_R = 200 V; T_j = 150 °C	100	µA
C_d	diode capacitance	f = 1 MHz; V_R = 0; see Fig.6	2	pF
t_{rr}	reverse recovery time	when switched from I_F = 30 mA to I_R = 30 mA; R_L = 100 Ω; measured at I_R = 3 mA; see Fig.8	50	ns

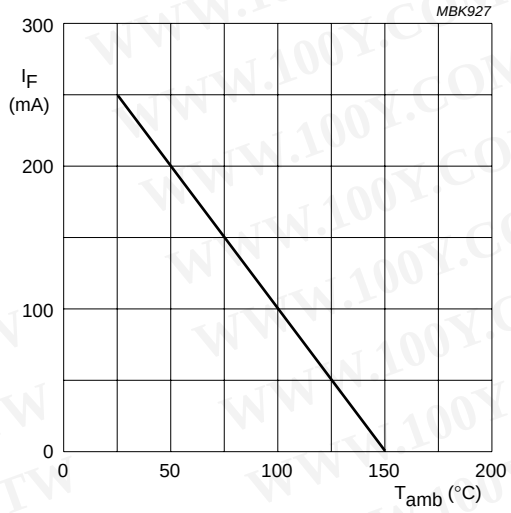
THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th(j-s)}$	thermal resistance from junction to soldering point	T_s = 90°C; note 1	130	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	note 2	366	K/W

Notes

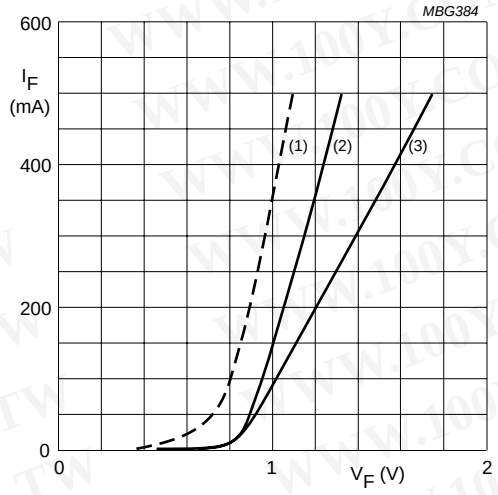
1. Soldering point of cathode tab.
2. Device mounted on an FR4 printed circuit board.

GRAPHICAL DATA



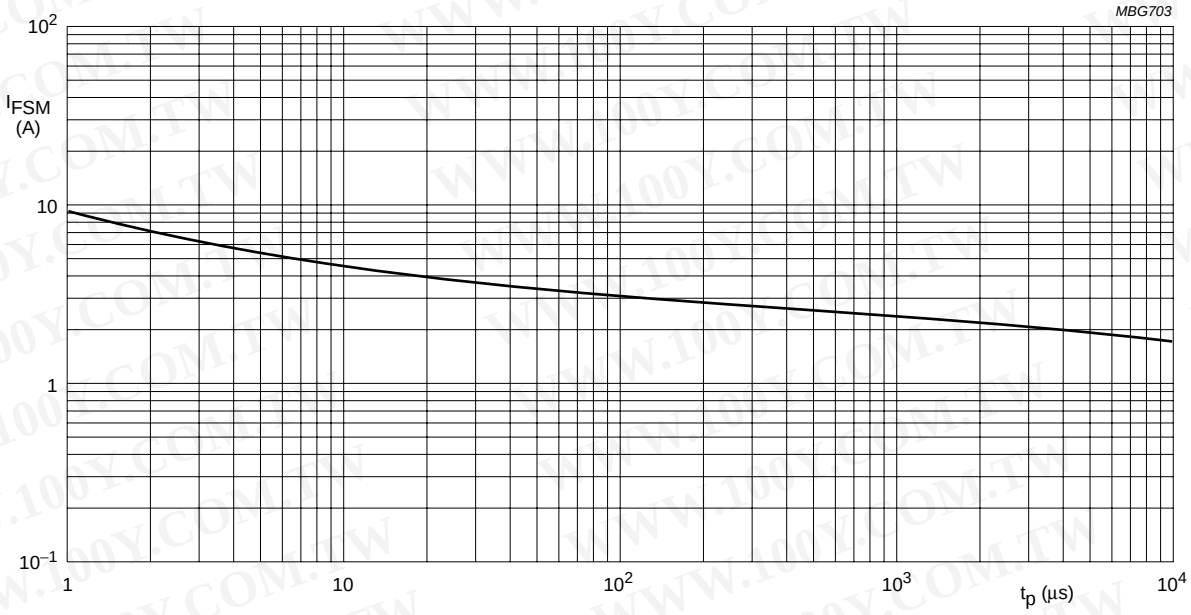
Device mounted on an FR4 printed-circuit board.

Fig.2 Maximum permissible continuous forward current as a function of ambient temperature.



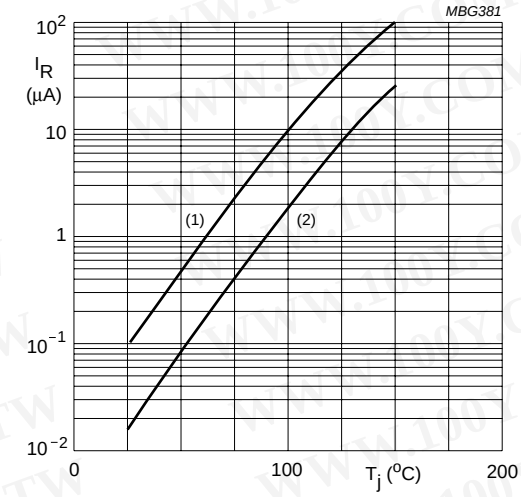
(1) T_j = 150 °C; typical values.
(2) T_j = 25 °C; typical values.
(3) T_j = 25 °C; maximum values.

Fig.3 Forward current as a function of forward voltage.



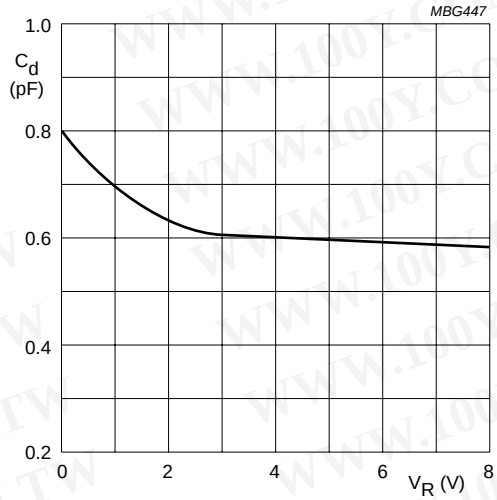
Based on square wave currents.
T_j = 25 °C prior to surge.

Fig.4 Maximum permissible non-repetitive peak forward current as a function of pulse duration.



(1) $V_R = V_{Rmax}$; maximum values.
(2) $V_R = V_{Rmax}$; typical values.

Fig.5 Reverse current as a function of junction temperature.



f = 1 MHz; T_j = 25 °C.

Fig.6 Diode capacitance as a function of reverse voltage; typical values.

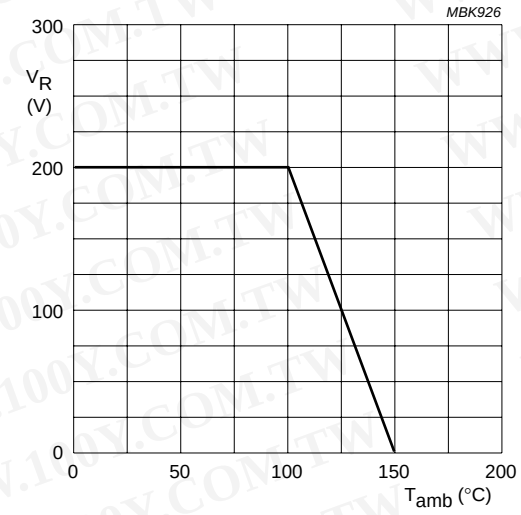
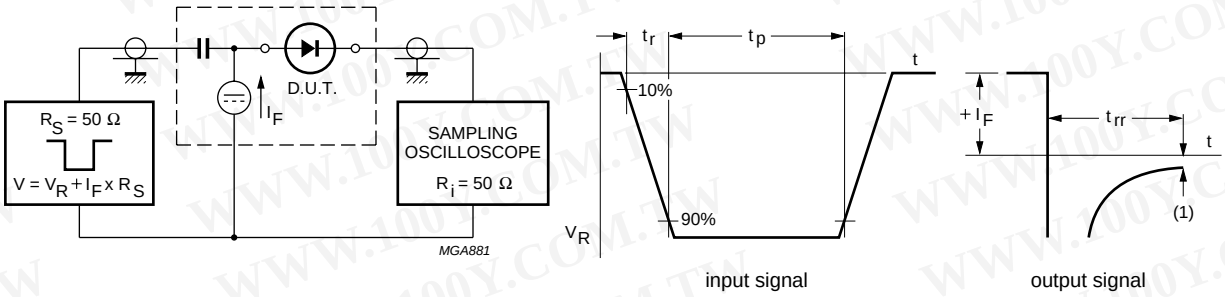


Fig.7 Maximum permissible continuous reverse voltage as a function of the ambient temperature.



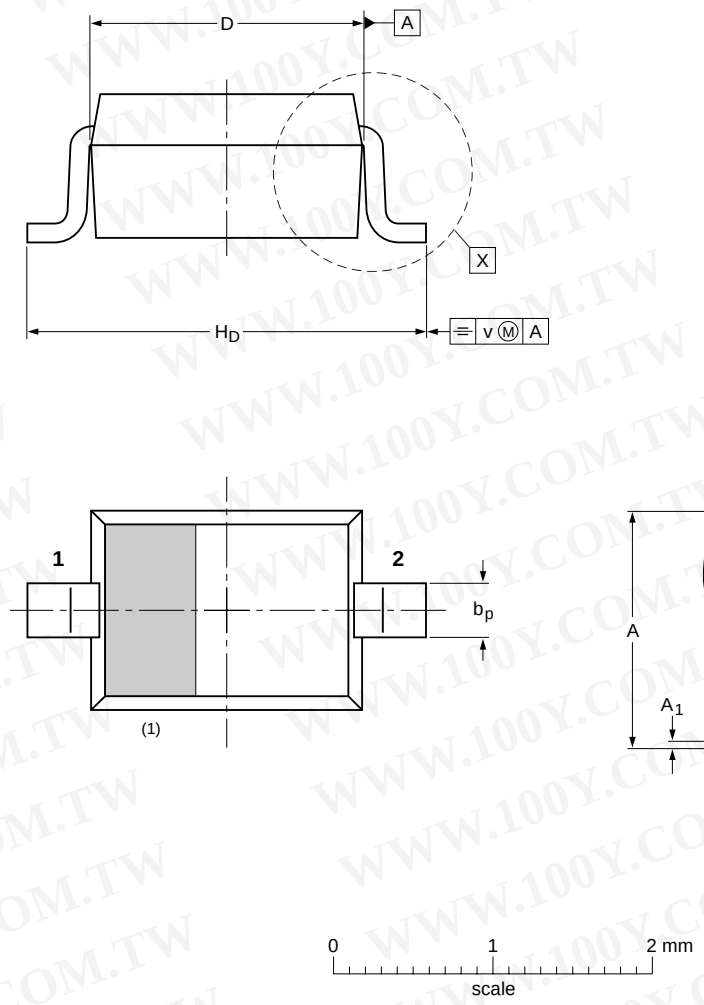
(1) I_R = 3 mA

Input signal: reverse pulse rise time t_r = 0.6 ns; reverse voltage pulse duration t_p = 100 ns; duty factor δ = 0.05;
Oscilloscope: rise time t_r = 0.35 ns;
Circuit capacitance C ≤ 1 pF (oscilloscope input + parasitic capacitance)

Fig.8 Reverse recovery time and waveforms.

PACKAGE OUTLINE

Plastic surface-mounted package; 2 leads **SOD323**



DIMENSIONS (mm are the original dimensions)

UNIT	A	A_1 max	b_p	c	D	E	H_D	L_p	Q	v
mm	1.1 0.8	0.05	0.40 0.25	0.25 0.10	1.8 1.6	1.35 1.15	2.7 2.3	0.45 0.15	0.25 0.15	0.2

Note

1. The marking bar indicates the cathode

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOD323			SC-76			~~03-12-17~~ 06-03-16

DATA SHEET STATUS

DOCUMENT STATUS[1]	PRODUCT STATUS[2]	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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NXP Semiconductors

Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

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